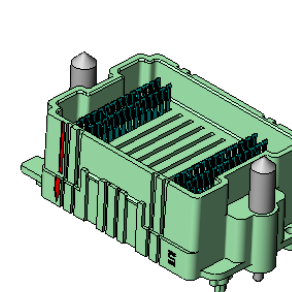
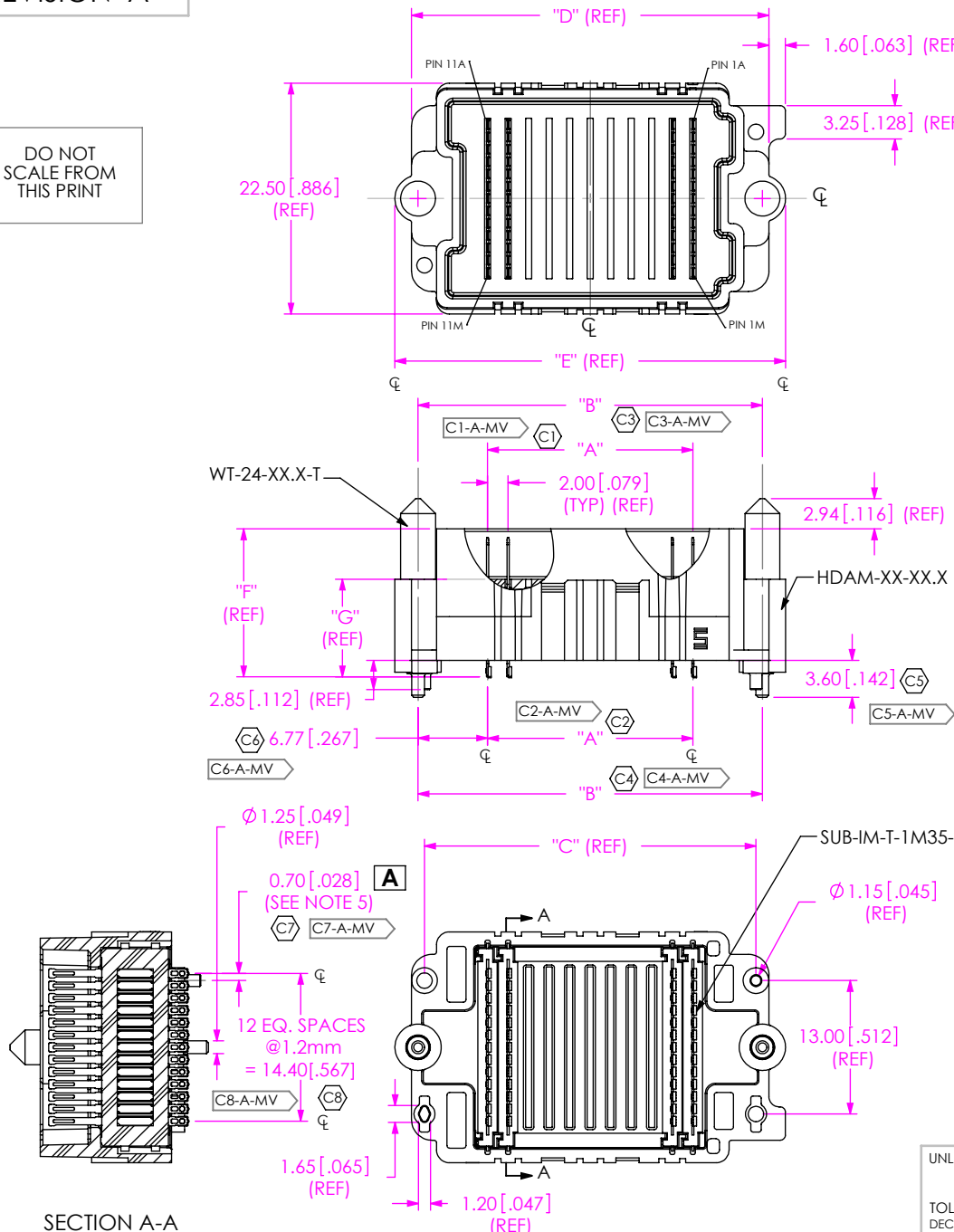


<u>No OF POSITIONS</u> (13 ROW PER POSITION) -11 -15 -23 <u>LEAD STYLE</u> -12.0: 12MM -17.0: 17MM <u>PLATING SPECIFICATION</u> -S: SELECTIVE, .000030 INCHES GOLD IN MATING AREA, MATTE TIN ON TAIL AND GUIDE PINS	<u>OPTION</u> -P: PICK & PLACE PAD (USE MPP-26-01-N) <u>SOLDER CHARGE MATERIAL</u> -1: 63%TIN / 37% LEAD -2: 95.5% TIN / 3.8% SILVER 0.7% COPPER (LEAD FREE) <u>No OF ROWS</u> -13
---	--

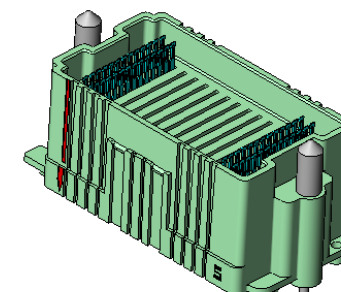
STYLE	"BODY CALLOUT"	"TERMINAL WAFER"	"GUIDE PIN"
-12.0	HDAM-XX-12.0	SUB-IM-T-1M35-12.0-S-X	WT-24-12.0-T
-17.0	HDAM-XX-17.0	SUB-IM-T-1M35-17.0-S-X	WT-24-17.0-T

TABLE 2		
STACK HEIGHT		
HDM LEAD STYLE	HDAF LEAD STYLE	
	-08.0	-18.0
-12.0	20.0MM	30.0MM
-17.0	25.0MM	35.0MM

No. OF POS.	LEAD STYLE	"A"	"B"	"C"	"D"	"E"	"F"	"G"
11	12.0	20.0 [787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	14.41 [567]	9.51 [374]
15	12.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	14.41 [567]	9.51 [374]
23	12.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	14.41 [567]	9.51 [374]
11	17.0	20.0 [787]	33.55 [1.321]	32.30 [1.272]	34.82 [1.371]	38.06 [1.498]	19.41 [764]	14.51 [571]
15	17.0	28.0 [1.102]	41.55 [1.636]	40.30 [1.587]	42.82 [1.686]	46.06 [1.813]	19.41 [764]	14.51 [571]
23	17.0	44.0 [1.732]	57.55 [2.266]	56.30 [2.217]	58.82 [2.316]	62.06 [2.493]	19.41 [764]	14.51 [571]



(-12.0 SHOWN)



(-17.0 SHOWN)

UNLESS OTHERWISE SPECIFIED,
DIMENSIONS ARE IN
MILLIMETERS [INCHES].
TOLERANCES ARE:

DECIMALS	ANGLES
.X: ± 0.3 [.01]	2°
.XX: ± 0.13 [.005]	
.XXX: ± 0.051 [.0020]	

PROPRIETARY NOTE

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.XXX: ±0.001 [0.0020]		CONSENT C
MATERIAL:	DO NOT SCALE	DRAWING

SHEET SCALE: 1.5:1

INSULATOR: LCP, COLOR: BLACK
CONTACT: COPPER ALLOY
WAFER MATERIAL: LCP, COLOR: BLACK
GUIDE PIN MATERIAL: BRASS
PICK AND PLACE PAD: COPPER ALLOY



DESIGNED WITH **SolidWorks**

SAMTEC

520 PARK EAST BLVD, NEW ALBANY, IN 47150
* PHONE: 812.944.6733 FAX: 812.948.5047
e-Mail: INFO@SAMTEC.COM CODE: 5532

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO. HDAM-XX-XX.X-X-13-X-X

BY: D KNOWLDEN 7/15/2005 SHEET 1 OF 2

NOTES:

1.  REPRESENTS A CRITICAL DIMENSION.
2. MINIMUM PUSHOUT FORCE: 2.22N[5 LB.] FOR WAFERS
3. CONNECTORS TO BE PACKAGED IN TRAYS.
4. USE THESE SURFACES TO MEASURE "G" DIMENSION.
5. DIMENSION FROM  OF END TAIL TO  OF -A PIN.

FIG. 1
-11: IT POSITION
(HDAM-11-12.0-X-13-X-X SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)

**DESIGNED & DIMENSIONED IN MILLIMETERS
(INCHES FOR REFERENCE ONLY)**

F:\DWG\MISC\MKTG\HDAM-XX-XX.X-X-13-X-X-MKT.SI.DRW

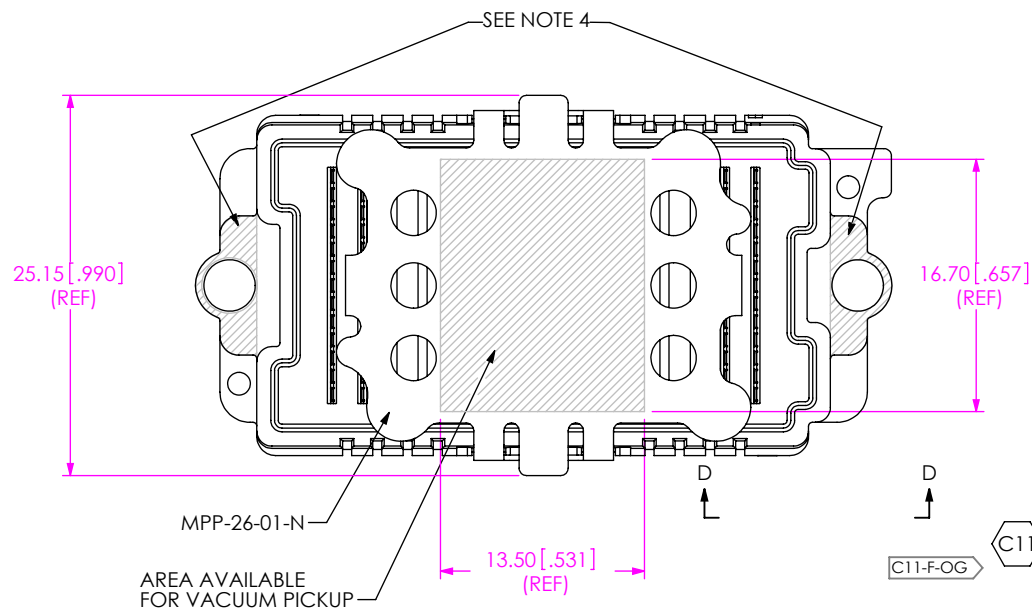
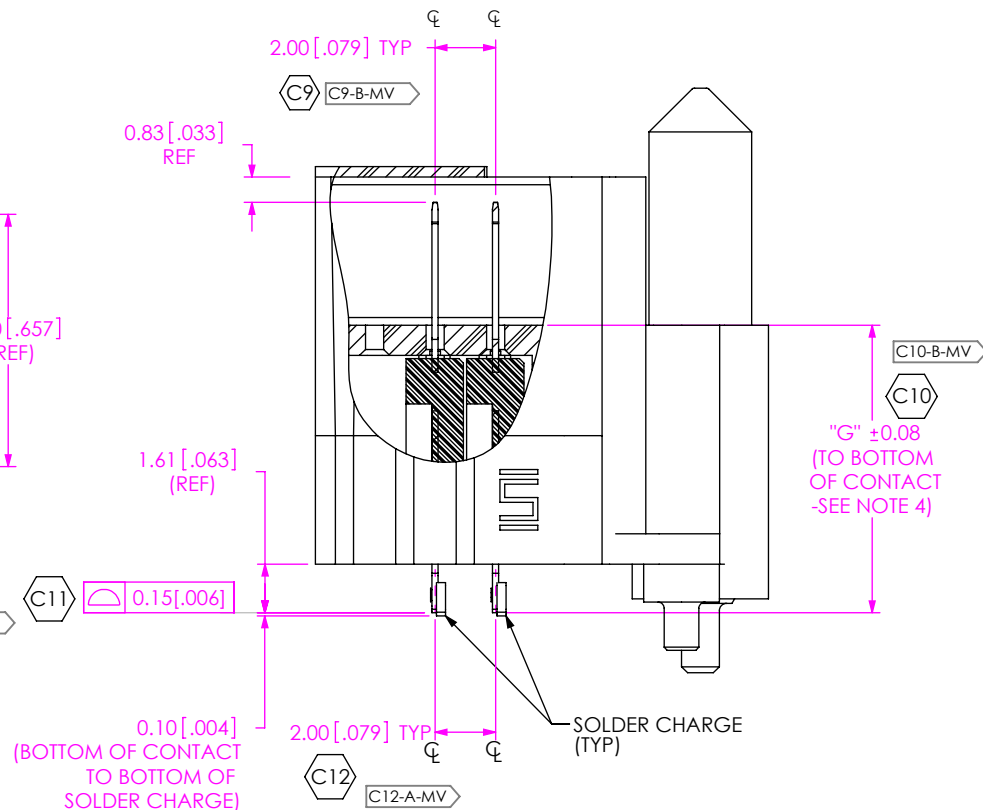
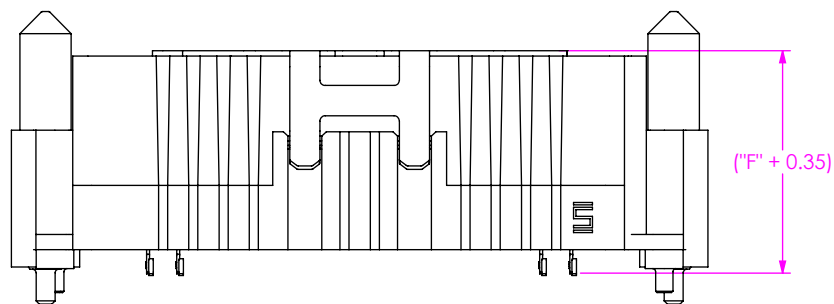


FIG. 2
-15: T5 POSITION
(HDAM-15-12.0-X-13-X-P SHOWN)
(SOME WAFERS NOT SHOWN FOR CLARITY)



VIEW D-D
SCALE 4:1

CRITICAL DIMENSION INSPECTION INSTRUCTION TABLE		
ASSEMBLY OPERATION	START-UP INSPECTION INSPECT CODE A	IN-PROCESS INSPECTION INSPECT CODE B
FILL WAFERS	C1, C2, C7, C8, C12	C9, C10
FILL WELD TABS	C2, C3, C4, C5, C6, C12	C10
INSTALL PAD	C2, C6, C12	N/A

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DO NOT SCALE DRAWING

SHEET SCALE: 2:1

SAMTEC

520 PARK EAST BLVD, NEW ALBANY, IN 47150
* PHONE: 812.944.6733 FAX: 812.948.5047
e-Mail: INFO@SAMTEC.COM CODE: 55322

DESCRIPTION:
2.0MM PITCH HD ARRAY TERMINAL ASSEMBLY

DWG. NO.
HDAM-XX-XX.X-X-13-X-X

BY:D KNOWLDEN 7/15/2005 SHEET 2 OF 2